

DESCRIPTION

~~DOUBLE SIDED POLISHING METHOD~~

TECHNICAL FIELD

[0001]

The present invention relates to a double-side polishing method for polishing both surfaces of a wafer at the same time while supplying a polishing agent.

BACKGROUND ART

[0002]

As the line width of semiconductor circuits is shrunk, stricter requirements for flatness of semiconductor wafers used as substrates of the circuits have been imposed. In such situations, large-diameter wafers are polished by a double-side polishing method, which ensures a higher polishing precision, instead of a conventional single-side polishing method.

Examples of the double-side polishing apparatus include a planetary gear type of double-side polishing apparatus, as depicted in FIG. 6, and a swinging type of double-side polishing apparatus, as depicted in FIG. 7. The planetary gear type of double-side polishing apparatus has a lower turn table and an upper turn table movable upward and downward, and is capable of pressing the upper turn table against the lower turn table to apply load to wafers interposed between the upper and lower turn tables. As depicted in FIG. 6, the double-side polishing apparatus 101 has a sun gear 107 provided inside the lower turn table and an internal gear 108 provided outside the lower turn table.

[0003]

Furthermore, between the upper and lower turn tables, carriers 105 for holding wafers are provided, and each of the carriers 105 engages at its periphery the sun gear and the internal

DESCRIPTION

DOUBLE-SIDE POLISHING METHOD

TECHNICAL FIELD

[0001]

The present invention relates to a double-side polishing method for polishing both surfaces of a wafer at the same time while supplying a polishing agent.

BACKGROUND ART

[0002]

As the line width of semiconductor circuits is shrunk, stricter requirements for flatness of semiconductor wafers used as substrates of the circuits have been imposed. In such situations, large-diameter wafers are polished by a double-side polishing method, which ensures a higher polishing precision, instead of a conventional single-side polishing method.

Examples of the double-side polishing apparatus include a planetary gear type of double-side polishing apparatus, as depicted in FIG. 6, and a swinging type of double-side polishing apparatus, as depicted in FIG. 7. The planetary gear type of double-side polishing apparatus has a lower turn table and an upper turn table movable upward and downward, and is capable of pressing the upper turn table against the lower turn table to apply load to wafers interposed between the upper and lower turn tables. As depicted in FIG. 6, the double-side polishing apparatus 101 has a sun gear 107 provided inside the lower turn table and an internal gear 108 provided outside the lower turn table.

[0003]

Furthermore, between the upper and lower turn tables, carriers 105 for holding wafers are provided, and each of the carriers 105 engages at its periphery the sun gear and the internal